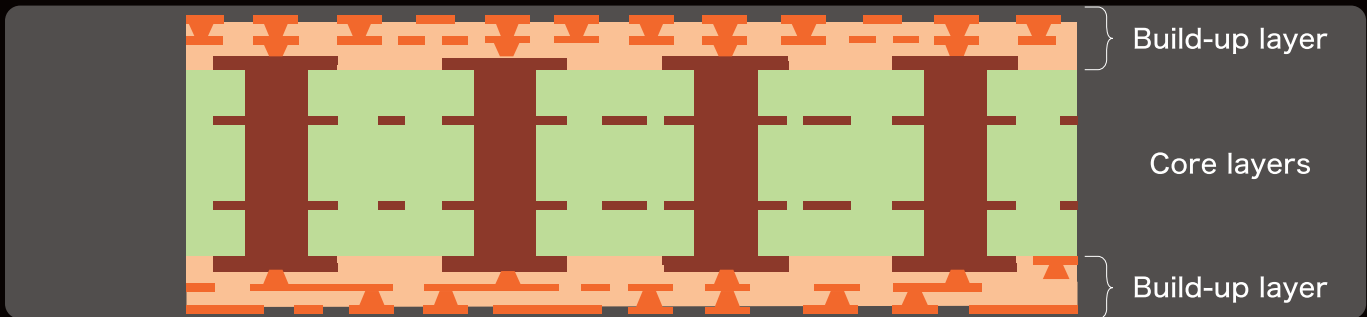


Acid copper plating additive  
for large diameter vias

# TOP LUCINA NSV LV

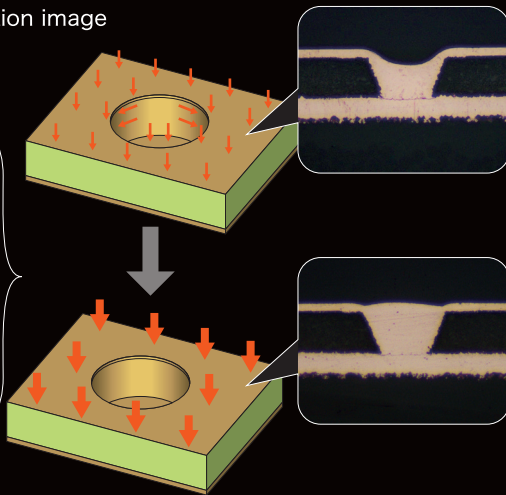
- ▶ Realize large diameter via filling
- ▶ Reduce influence by pattern width and pattern density
- ▶ Can use for through hole filling
- ▶ Can use for build-up to core layers



## Mechanism

↓: Leveler inhibition image

Decrease N based additive concentration  
+  
Increase charge density

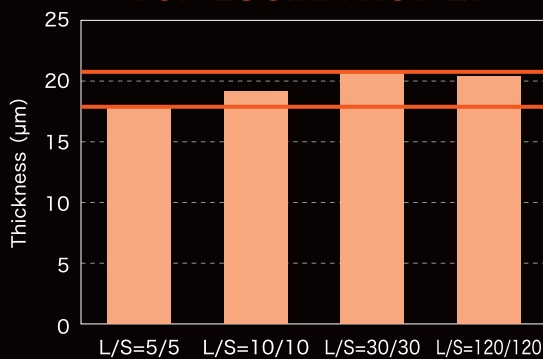


## For large-diameter via and through hole filling

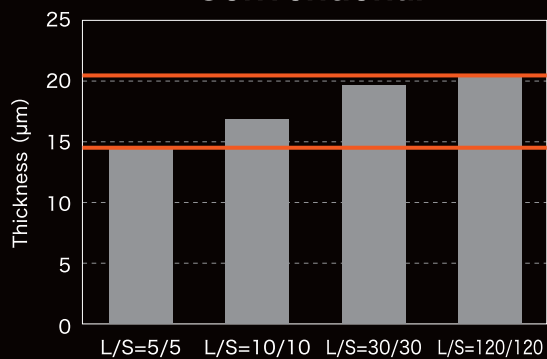
	Via filling	Through hole filling
Diameter	150μm	Diameter 80μm
Depth	130μm	Board thickness 200μm

## Reduce influence by pattern width and pattern density

### TOP LUCINA NSV LV



### Conventional



Surface thickness 18μm